

GXO-L31 - 1.8 ~ 3.3V LVDS Oscillator

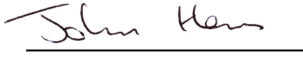
Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Base	Au Plating	Co	7440-48-4	0.156	0.68
	Au Plating	Au	7440-57-5	0.000	0.00
	Ceramic	Al ₂ O ₃	1344-28-1	14.480	63.11
	Ceramic	SiO ₂	14808-60-7	0.704	3.07
	Ceramic	CaO	1305-78-8	0.110	0.48
	Ceramic	MgO	1309-48-4	0.094	0.41
	Ceramic	Cr ₂ O ₃	1308-38-9	0.110	0.48
	Ceramic	Mo	7439-98-7	0.157	0.68
	Metallization	W	7440-33-7	3.482	15.18
	Metallization	Mo	7439-98-7	0.108	0.47
	Ni Plating	Fe	7439-89-6	0.449	1.96
	Ni Plating	Ni	7440-02-0	0.112	0.49
	Seal Ring	Tl	7440-28-0	1.210	5.27
	Seal Ring	Fe	7439-89-6	0.650	2.83
	Seal Ring	Ni	7440-02-0	0.381	1.66
	Solder	Co	7440-48-4	0.631	2.75
	Solder	Ag	7440-22-4	0.111	0.48
Cap	Kovar	Fe	7439-89-6	1.836	50.10
	Kovar	Ni	7440-02-0	0.987	26.93
	Kovar	Co	7440-48-4	0.580	15.83
	Kovar	Mn	7439-96-5	0.015	0.41
	Kovar	Si	7440-21-3	0.003	0.08
	Kovar	C	7440-44-0	0.000	0.00
	Ni Plating	Ni	7440-02-0	0.219	5.98
	Ni Plating	P	7723-14-0	0.025	0.68
Crystal	Crystal	Epoxy resin trade secret	0	0.484	69.64
	Crystal Adhesive	Ni	7440-02-0	0.147	21.15
	Crystal Adhesive	Ag	7440-22-4	0.026	3.74
	Crystal Adhesive	Silicones/siloxanes	68037-58-1	0.026	3.74
	Crystal Electrode	SiO ₂	14808-60-7	0.012	1.73
	Crystal Electrode	Ag	7440-22-4	0.000	0.00
H/IC	Adhesive	Au	7440-57-5	0.188	27.33
	Adhesive	Au	7440-57-5	0.063	9.16
	IC	Cu	7440-50-8	0.147	21.37
	IC	Si	7440-21-3	0.001	0.15
	IC	Al	7429-90-5	0.000	0.00
	IC	P	7723-14-0	0.000	0.00
	IC	B	7440-42-8	0.000	0.00
	IC	As	7440-38-2	0.000	0.00
	IC	TiO ₂	13463-67-7	0.000	0.00
	IC	W	7440-33-7	0.000	0.00
	IC	Cu	7440-50-8	0.002	0.29

Material Composition Data



Product: GXO-L31

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Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
H/IC	Wire	Other		0.287	41.72
Total Mass:				27.993 mg	
					
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